

MPH 3 (MHP3-MHPU3)

High Power, High Current, Silver Ribbon Leaded Capacitors

Features

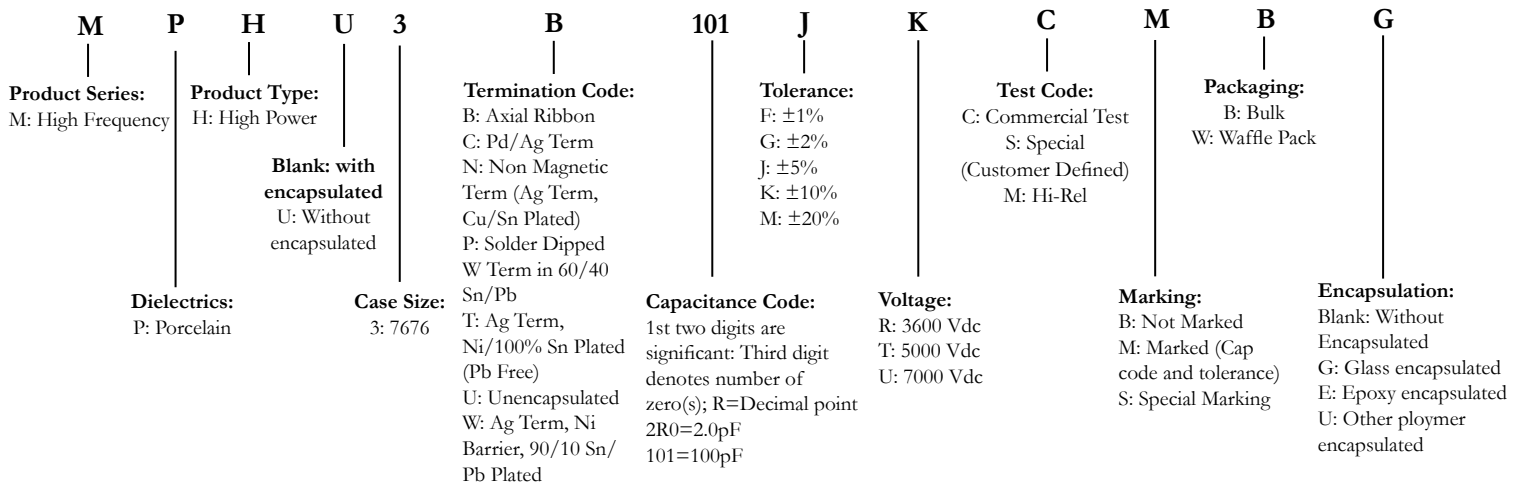
- Capacitance Range: 82pF to 620pF
- High Q Low ESR/ESL
- High RF Power
- Ultra Stable Performance
- Operating Voltages
 - DC Voltage: 3600Vdc to 7000Vdc
 - RF Voltage: 2500Vrms to 5000Vrms
- RF Current Rating 12A rms
- Available with Encapsulation Option, Chip and Leaded Configurations

Applications

- MRI Coils
- HF/RF Power Amplifiers
- Plasma Chambers
- Antenna Tuning
- High Power RF Transmitters
- Inductive Heating
- Semiconductor Equipment



AFM Part Number Code



Specification and Performance:

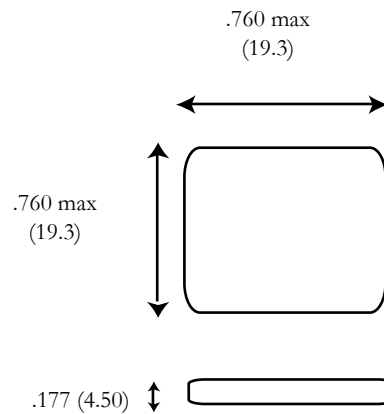
Piezoelectric and Aging Effect:	None Exhibited
Temperature Range:	-55°C to +125°C
Temperature Coefficient of Capacitance:	+90±30ppm/°C
Quality Factor (Q) :	>10,000 (1pF~1000pF) at 1MHz; >10,000 (1100pF~5100pF) at 1KHz
Insulation Resistance (IR, at Rated Voltage):	10 ⁵ MΩ min. at +25°C at rated WVDC; 10 ⁴ MΩ min. at +125°C at rated WVDC
Capacitance Drift:	±0.02% or ±0.02pF, whichever is greater

Standard Capacitance Values

CAP CODE	CAP (pF)	TOL	WVDC V	CAP CODE	CAP (pF)	TOL	WVDC V
820	82	F, G, J, K, M	7000	271	270	F, G, J, K, M	5000
910	91			301	300		
101	100			331	330		
111	110			361	360		
121	120			391	390		
131	130			431	430		
151	150			471	470		
161	160			511	510		
181	180			561	560		
201	200			621	620		
221	220						3600
241	240						

Chip Dimensions All Dimensions are in Inches (mm)

Dimensional Data	Length of Chip/ Encapsulated (L) in (mm)	.760 (19.3)/ 1.062 (26.97) max after encapsulation
	Width of Chip / Encapsulated (W) in (mm)	.760 (19.3)/ 1.062 (26.97) max after encapsulation
	Thickness of Chip (T) in (mm) (Encapsulated) (max)	.177 (4.50) May Increase to .236 (5.99) Max. After Glass Encapsulation
	Ribbon Lead (Axial) in (mm)	Length: .750 (19.05) Width: .350 (8.89) Thickness: .010 (0.25)



Lead Options All Dimensions are in Inches (mm)

Construction Features	Ribbon Led	Lead Material	Pure Silver (99.9%)
		Lead Bonding	Silver Brazed
		Encapsulation	Glass-Ceramic Coated on all 6 Sides Epoxy Encapsulation Optional

